Hybrid 7p167 Traveler

February 9, 2000

1 Connectivity

Repairs on shorts:

Fixes for opens: Bus 3B open on chip 3; fixed with wirebond.

2 Chips

The following chips were assembled on this hybrid (in the order that the chips get read out):
Hybrid 7P167 has die: 175-018 175-019 175-020 175-023 175-024 175-025 175-026

3 Data Analysis Summary

The following summarizes the findings of the Burn-in data analysis program. The first chip in the readout name is numbered 0.

```
% Hybrid 7p167 classification info. Created 11:41:21 02/09/00

Hybrid 7p167 quality: fair
Chip classification: good good fair good good good good
Bad channels: none
Bad cells: none
Random bad capacitors (chip-cell-channel): 2-10-55 2-13-55 2-15-55
   2-17-55 2-26-54 2-26-55 2-27-55 2-39-55
Channels at pedestal needed for DCMS: 34.6 34.7 31.6 33.7 34.6 32.7 34.7
```

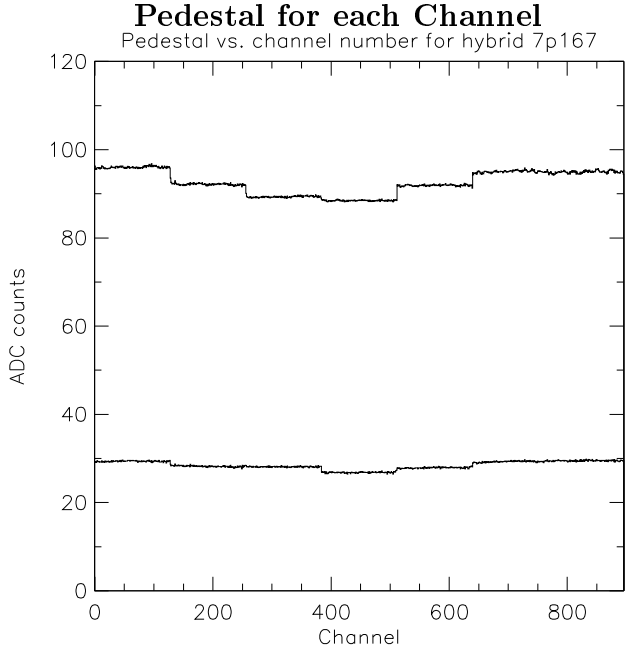
4 Comments

Encapsulated. FE DV finger gold bonds. HV tested.

5 Pedestal

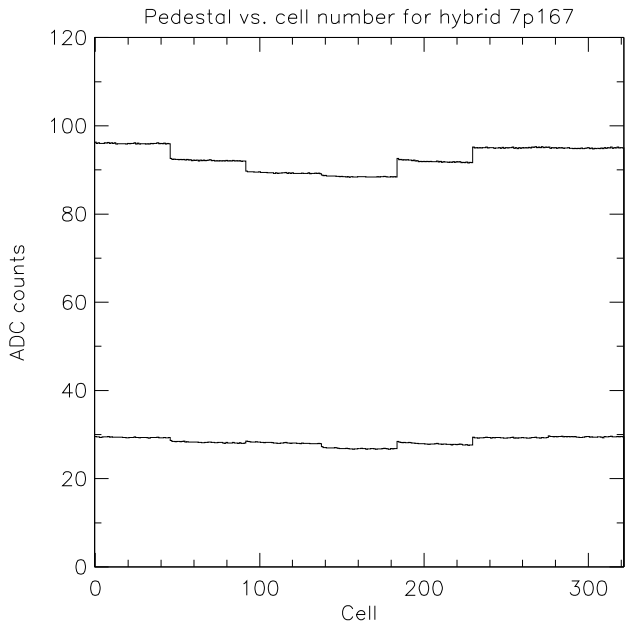
The following plot shows the pedestals vs. channel number with and without charge injection:

Pedestal for each Channel



The following plot shows the average pedestal vs. pipeline cell ID with and without charge injection. The x-axis is cell ID offset by 46 for each chip. Thus cell ID 5 for chip 1 is at x=5, chip 2 at x=51, chip 3 at x=97, etc.

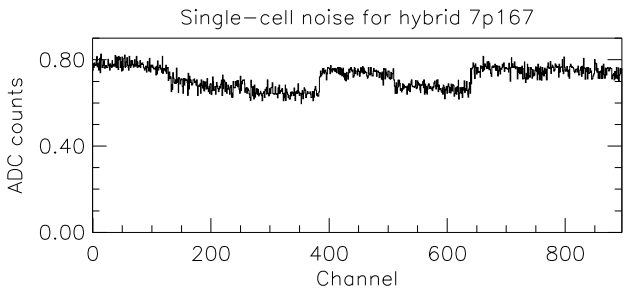
Pedestal vs. Pipeline Cell ID

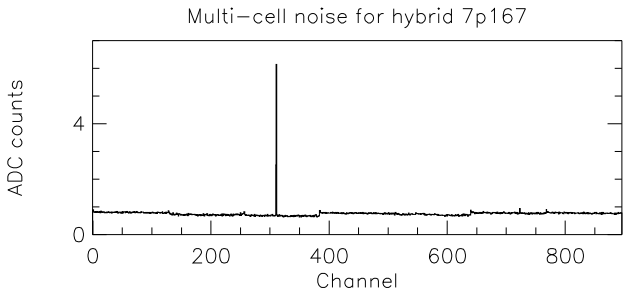


6 Noise

The following plots show the single-cell and multi-cell RMS noise:

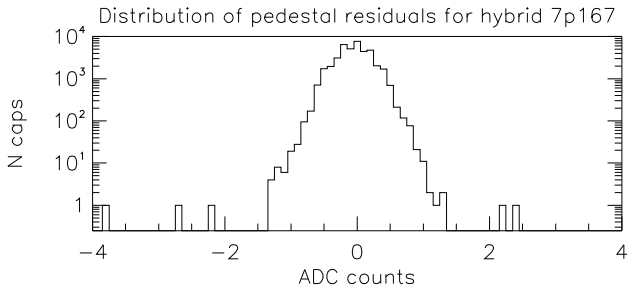
RMS Noise

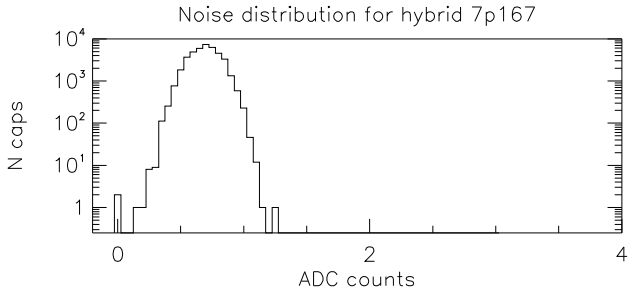




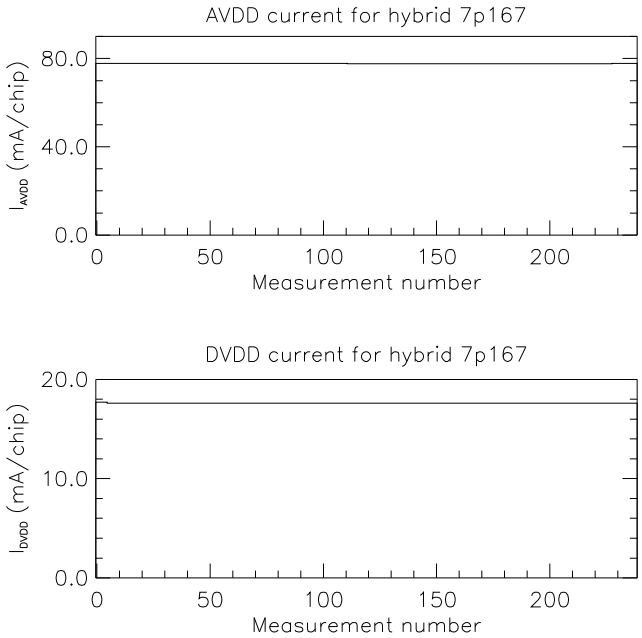
The following are histograms of the pedestal of each pipeline capacitor relative to the chip average (top); and the RMS noise of each capacitor (bottom):

Distribution of Pedestals and Noise





7 Currents

The following plots show the supply currents per chip as a function of measurment number. Currents are measured approximately every 10 minutes:

Supply Currents During Burn-in